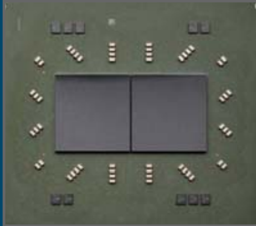
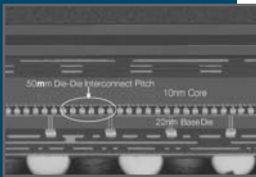
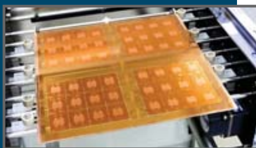
Advanced Packaging Update:
Market and Technology Trends

Vol. 3-1122







This issue of the Advanced Packaging Update includes an analysis of the impact of lower consumer spending; lockdowns in China, and U.S. export restrictions. OSAT financials are discussed. An updated analysis of the build-up substrate supply and demand is presented. North American substrate suppliers are described. Thermal issues and material developments are presented. A special section focuses on EV charging stations.

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